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Receipt is hereby acknowledged for the following in the United States Patent and Trademark Office:

In re Patent Application of: Xiao-Chun Mu et al.

Title: Microelectronic Package Having an Integrated Heat Sink and Build-Up Layers

Serial No.: 09/733289

Filing Date: December 8, 2000

CONTENTS: A Supplemental Information Disclosure Statement (2 pgs.), Form 1449 (1 pg.), and copies of 5 cited documents; Copy of International Search Report in PCT/US01/49898 (6 pgs.); a Return Postcard and TRANSMITTAL SHEET.

Mailed: July 24, 2003
AMM/kml



Docket No.: 884.798US1
Due Date: N/A



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S/N 09/733289

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Xiao-Chun Mu et al.	Examiner:	DiLinh Nguyen
Serial No.:	09/733289	Group Art Unit:	2814
Filed:	December 08, 2000	Docket:	884.798US1
Title:	MICROELECTRONIC PACKAGE HAVING AN INTEGRATED HEAT SINK AND BUILD-UP LAYERS		
Assignee:	Intel Corporation		

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Supplemental Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. §1.97(c)(1) and 37 C.F.R. §1.97(e)(1), Applicants state that each item of information contained in the Supplemental Information Disclosure Statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the Supplemental Information Disclosure Statement. A copy of the International Search Report citing these references is enclosed.

It is believed that no fee or statement is required with the Supplemental Information Disclosure Statement. However, if a final action under §1.113, a notice of allowance under §1.311, or an action that otherwise closes prosecution in the application has been mailed, the Commissioner is hereby authorized to charge the required fees to Deposit Account No. 19-0743 in order to have this Supplemental Information Disclosure Statement considered.

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Serial No :09/733289

Filing Date: December 08, 2000

Title: Microelectronic Package Having an Integrated Heat Sink and Build-Up Layers

Assignee: Intel Corporation

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Dkt: 884.798US1 (INTEL)

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

XIAO-CHUN MU ET AL.

By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

Attorneys for Intel Corporation

P.O. Box 2938

Minneapolis, Minnesota 55402

(612) 373-6970

Date

July 24, 2003

By

Charles E. Steffey

Reg. No. 25,179

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 24 day of July, 2003.

Name

KACIA LEE

Signature

Kacia Lee

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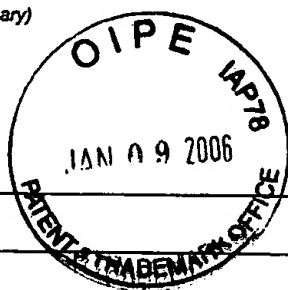
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Substitute for form 1449A/PTO

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(Use as many sheets as necessary)



Complete if Known

Application Number	09/733289
Filing Date	December 8, 2000
First Named Inventor	Mu, Xiao-Chun
Group Art Unit	2814
Examiner Name	Nguyen, DiLinh

Sheet 1 of 1

Attorney Docket No: 884.798US1

US PATENT DOCUMENTS

Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	Filing Date If Appropriate
	US-5,048,179	09/17/1991	Shindo, M., et al.	29	840	02/14/1990

FOREIGN PATENT DOCUMENTS

Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	T ²
	EP-0604005	06/29/1994	Wachtler, Kurt P.			
	JP-11-233678	08/27/1999	Kazunori, Akaho			
	JP-3-155144	07/03/1991	Ikegawa, Gihei			
	JP-62-4351	10/01/1987	Saito, Tamio			

OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
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EXAMINER

DATE CONSIDERED

Substitute Disclosure Statement Form (PTO-1449)

* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 608. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. ¹ Applicant's unique citation designation number (optional) ² Applicant is to place a check mark here if English language Translation is attached